



LED545-01

- Green LED
- 545 nm, 2 mW
- Chip Material: InGaN
- 5 mm Clear Mold, Epoxy Resin
- Viewing Angle: 16°



Description

LED545-01 contains a InGaN LED mounted on a lead frame hermetically sealed with a clear epoxy lens. On forward bias, it emits a power radiation of typical **2 mW** at a peak wavelength at **545 nm**.

Maximum Ratings ($T_{CASE}=25^{\circ}C$)

Parameter	Symbol	Values		Unit
		Min.	Max.	
Power Dissipation	P_D		180	mW
Forward Current	I_F		50	mA
Pulse Forward Current *1	I_{FP}		100	mA
Reverse Voltage	V_F		5	V
Thermal Resistance	R_{THJA}		330	K/W
Junction Temperature	T_J		100	°C
Operating Temperature	T_{CASE}	- 40	+ 85	°C
Storage Temperature	T_{STG}	- 40	+ 100	°C
Lead Solder Temperature *2	T_{SLD}		+ 265	°C

*1 duty=1%, pulse width = 10 μ s

*2 must be completed within 3 seconds

Electro-Optical Characteristics ($T_{CASE}=25^{\circ}C$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Peak Wavelength	λ_P	$I_F=20mA$	535	545	555	nm
Half Width	$\Delta\lambda$	$I_F=20mA$		36		nm
Dominant Wavelength	λ_D	$I_F=20mA$				
Forward Voltage	V_F	$I_F=20mA$		3.2		V
Radiated Power *1	P_O	$I_F=20mA$		2		mW
Radiant Intensity *2	I_E	$I_F=20mA$		9.3		mW/sr
Brightness	I_V	$I_F=20mA$		7		cd
Viewing Angle	φ	$I_F=20mA$		16		deg.

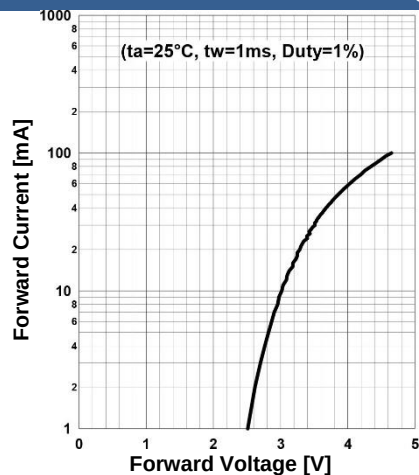
*1 measured by S3584-08

*2 measured by Tektronix J-6512

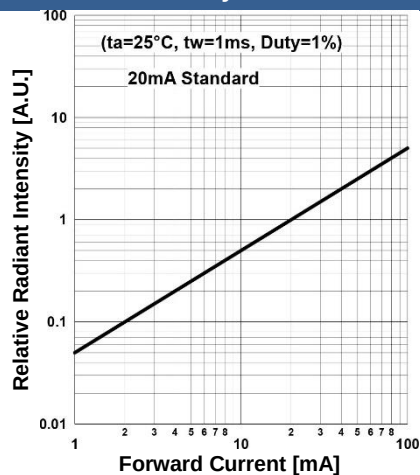


Typical Performance Curves

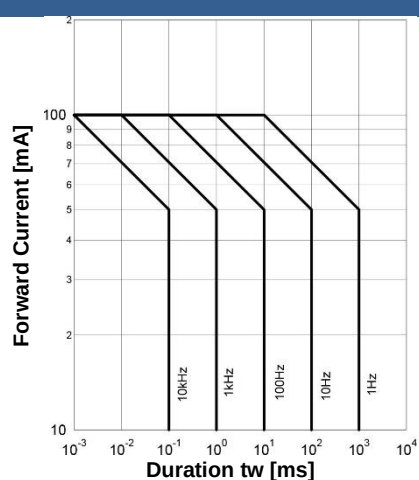
Forward Current vs. Forward Voltage



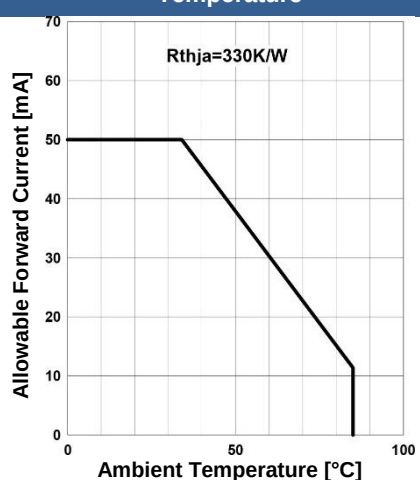
Rel. Radiant Intensity vs. Forward Current



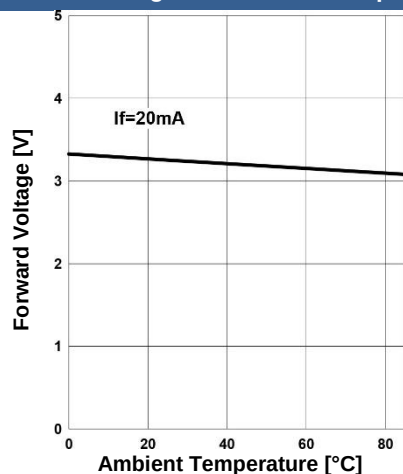
Forward Current vs. Pulse Duration



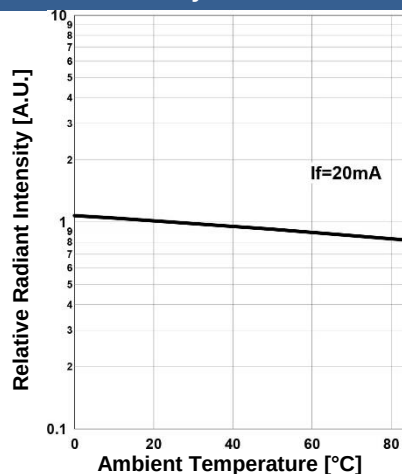
Allowed Forward Current vs. Ambient Temperature



Forward Voltage vs. Ambient Temperature

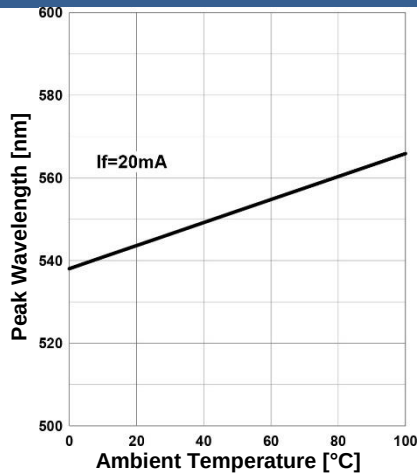


Rel. Radiant Intensity vs. Ambient Temperature

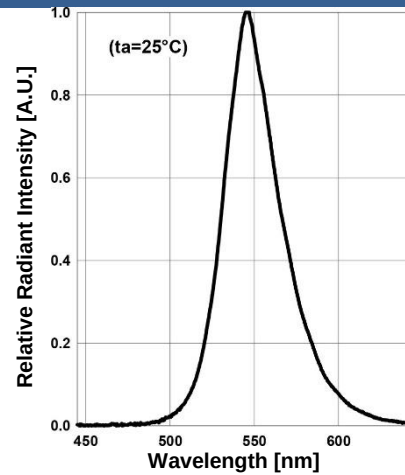




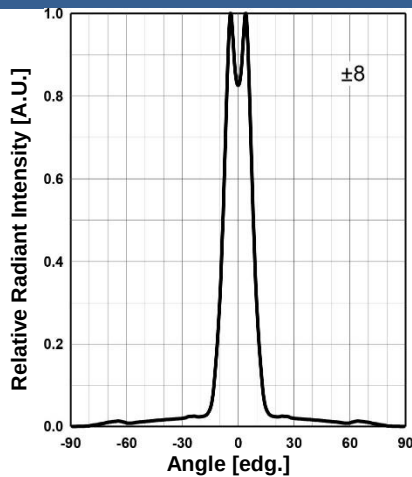
Peak Wavelength vs. Ambient Temperature



Relative Spectral Emission



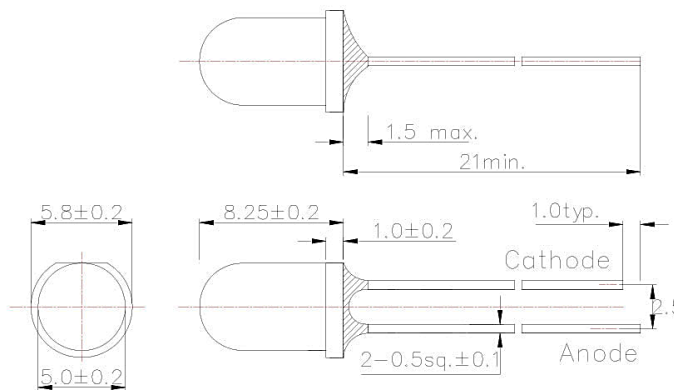
Radiation Characteristics



Outline Dimensions

LED545-01

5 mm



Lead	Description
Short Pin	LED Cathode
Large Pin	LED Anode

All Dimensions in mm

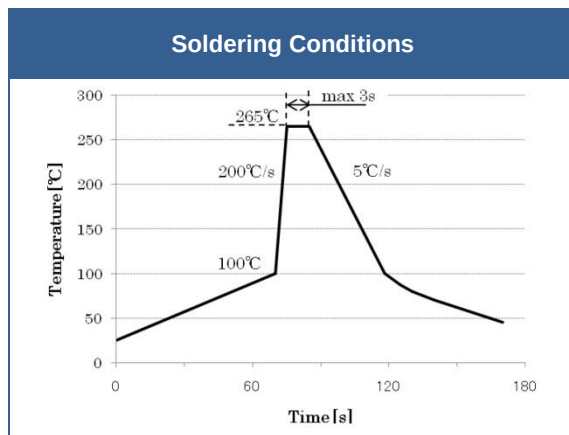
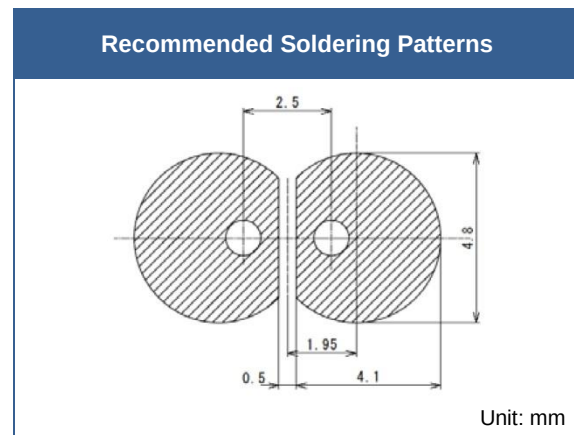


Precautions

Soldering:

- Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering
- Do not solder the LED closer than 3 mm from the base of the lead.

Recommended soldering conditions:



Above table specifies the maximum allowed duration and temperature during soldering. It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

Cleaning:

Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroform, trichloroethylene, or MKS

DO NOT USE ultrasonic cleaners

Static Electricity:

LEDs are sensitive to electrostatic discharge (ESD). Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

Radiation:

During operation these LEDs do emit light, which could be hazardous to skin and eyes, and may cause cancer. Do avoid exposure to the emitted light. Protective glasses if needed. It is further advised to attach a warning label on products/systems.

Operation:

Do only operate LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device.

Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.